Product Change Notification

Change Notification #: **114738-00 - 00**

Change Title: **Hot-swap Drive Cage Kit FUP8X25S3HSDK**
Hot-swap Backplane PCIe Combination
Drive Cage Kit for P4000 Server Chassis
FUP8X25S3NVDK and
Intel® Server Chassis P4304XXMUXX
PCN 114738-00
Label

Date of Publication: **June 30, 2016**

Key Characteristics of the Change:

Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	July 8, 2016

Description of Change to the Customer:

Intel is implementing the following change on the Intel® Server Chassis P4304XXMUXX, Hot-Swap Drive Cage FUP8X25S3HSDK and Hot-Swap Drive Cage FUP8X25S3NVDK.

Based on California State Regulations we have updated of the package label by adding warning content for cable products containing Diisononyl phthalate (DINP) and/or Diisodecyl phthalate (DIDP) that are listed under Proposition 65 of California law. There is no change to the product itself. Please see Figure-1 for details.

PRODUCT CODE: P4304XXMUXX
VERSION #:
CARTON #:
SERIAL #:
UPC CODE:
EAN CODE:
MM #:
BATCH #:
PACK DATE:
QTY:
MODEL: P4000
MADE IN CHINA
INTEL CORPORATION

WARNING: This product contains a chemical known to the State of California to cause cancer.

Figure-1: Adding Warning: This product contains a chemical known to the State of California to cause cancer.

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	TA
P4304XXMUXX	937011	H45587-003
FUP8X25S3HSDK	936425	H46616-002
FUP8X25S3NVDK	936426	H46618-001

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
June 30, 2016	00	Originally Published PCN

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#114738-00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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